

PC33H13 V1

Product Specification



Approval Sheet

PC33H13 V1
Product Specification



Product	White SMD LED
Part Number	PC33H13 V1
Issue Date	2015/10/15



Feature

- \checkmark White SMD LED (L x W x H) of 3.2 x 3.0 x 0.6 mm
- ✓ ANSI-Ellipse binning
- ✓ Dice Technology : InGaN
- ✓ Qualified according to JEDEC moisture sensitivity Level 3
- ✓ Environmental friendly; RoHS compliance
- ✓ Packing: 3,000 or 1,000 pcs/reel

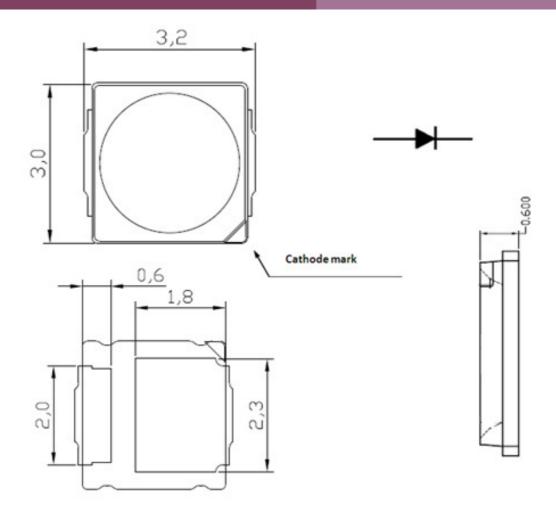
Applications

- ✓ Reading lights
- ✓ Security / garden lighting
- ✓ General lighting
- √ Indoor and outdoor commercial lighting



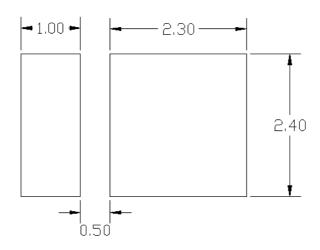
Outline Dimension

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Unit: mm, Tolerance: ±0.1mm

■ Recommended Soldering Pad





Performance

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■ Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage ⁽¹⁾	V_{F}		29	32	35	V
Color Rendering Index ⁽²⁾	Ra		80	-	-	-
Color Rendering Index ⁽³⁾	R9	$I_F = 40 \text{ mA}$	0			
View Angle	θ		-	120	-	deg
Thermal Resistance ⁽⁴⁾	R _{th}		-	15	-	°C/W

- (1) The Forward Voltage tolerance is ±1V
- (3) The R9 is measured at Ta=85 $^{\circ}$ C and tolerance is ±6.
- (4) Thermal resistance is calculated from junction to solder

■ Luminous Flux (Ta=25°C)

ССТ	Condition	Rank	
2600K~3700K	1 40 m A	EU, EV, EW	
3700K~7000K	$I_F = 40 \text{ mA}$	EV, EW, EX	

^{*} The luminous flux tolerance is ± 7%

Absolute Maximum Ratings

Parameter	Symbol	value	Unit
DC Forward Current ⁽¹⁾	I _F	50	mA
Power Dissipation	P _D	2	W
Pulse Forward Current (2)	I _{FP}	80	mA
Storage Temperature	T _{stg}	-40 ~ 100	°C
Operating Temperature	T_{opr}	-40 ~ 100	°C
Junction Temperature	T_J	125	°C
Assembly Temperature	-	260 (max. 10sec)	°C

- (1) Proper current rating must be observed to maintain junction temperature below maximum at all time
- (2) IFP Condition: Duty 1/10, Pulse within 10msec



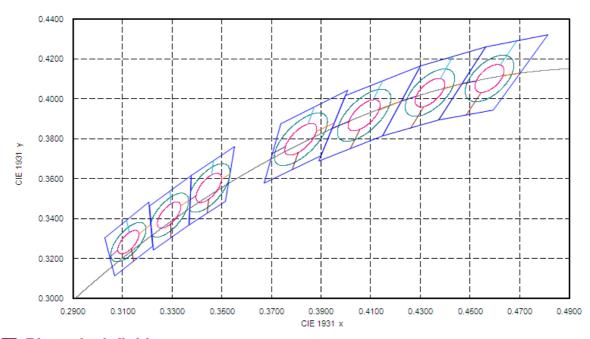
Binning

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Chromaticity Coordinates

The PC33H13 V1 is hot color targeted so that at 85 °C, the color is within ANSI while typical bin structured at 85 °C.

In application conditions, the LED temperature rises and at 85 ℃ the typical color bins will be as shown.



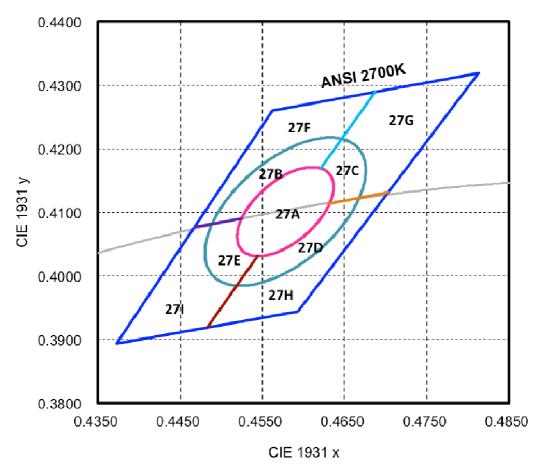
Bin code definition

V _F Rank	Luminous Flux Rank	CIE Rank
0	EU	27A

V _F Rank	Condition	Min.	Max.
0	1 40m A	29	31
1	$I_F = 40 \text{mA}$ $Ti = 25 ^{\circ}C$	31	33
2	1]=25 (33	35

Luminous Flux Rank	Condition	Min.	Max.
EU		110	120
EV	$I_F = 40 \text{ mA}$	120	130
EW	Tj=25°C	130	140
EX		140	150

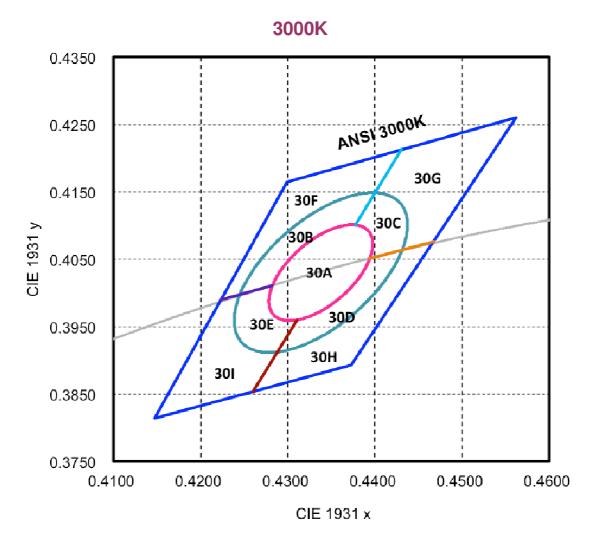




Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	a	b	Angle
2700K	Single 3-step	(0.4578,	0.00810	0.00420	53.70°
	MacAdam ellipse	0.4101)			
2700K	Single 5-step	(0.4578,	0.01350	0.00700	53.70°
	MacAdam ellipse	0.4101)			

	CIE-X	CIE-Y
2700K	0.4813	0.4319
	0.4562	0.4260
	0.4373	0.3893
	0.4593	0.3944

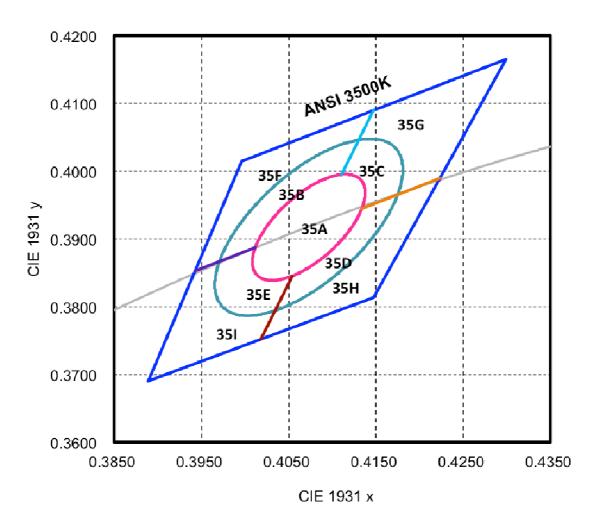




Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	а	b	Angle
3000K	Single 3-step	(0.4338, 0.403)	0.00834	0.00408	53.22°
	MacAdam ellipse				
3000K	Single 5-step	(0.4338, 0.403)	0.01390	0.00680	53.22°
	MacAdam ellipse				

	CIE-X	CIE-Y
3000K	0.4562	0.426
	0.4299	0.4165
	0.4147	0.3814
	0.4373	0.3893

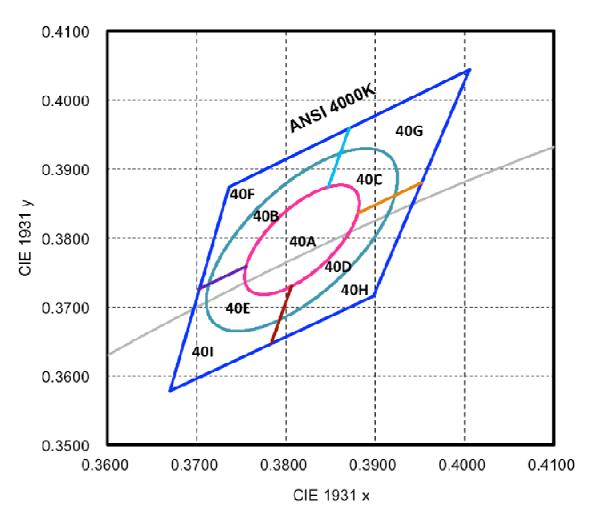




Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	а	b	Angle
3500K	Single 3-step	(0.4073,	0.00927	0.00414	53.22°
	MacAdam ellipse	0.3917)			
3500K	Single 5-step	(0.4073,	0.01545	0.00690	53.22°
	MacAdam ellipse	0.3917)			

	CIE-X	CIE-Y
	0.4299	0.4165
3500K	0.3996	0.4015
330010	0.3889	0.3690
	0.4147	0.3814

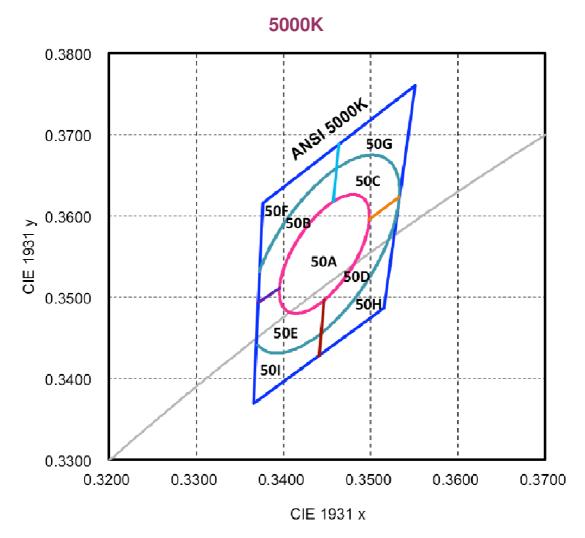




Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	a	b	Angle
4000K	Single 3-step	(0.3818,	0.00939	0.00402	53.72°
	MacAdam ellipse	0.3797)			
4000K	Single 5-step	(0.3818,	0.01565	0.00670	53.72°
	MacAdam ellipse	0.3797)			

	CIE-X	CIE-Y
4000K	0.4006	0.4044
	0.3736	0.3874
	0.3670	0.3578
	0.3898	0.3716

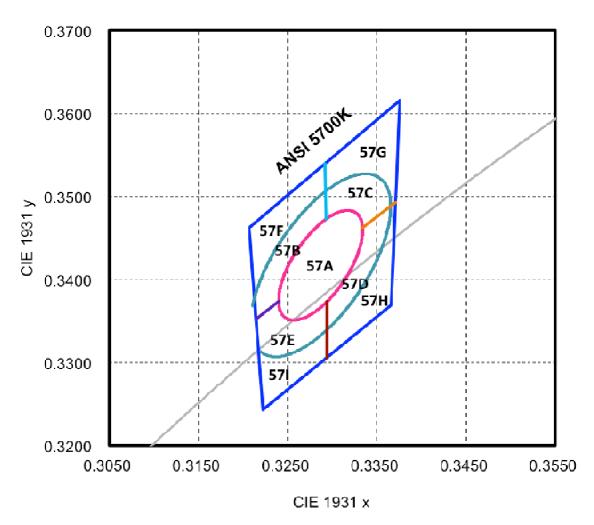




Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	a	b	Angle
5000K	Single 3-step	(0.3447,	0.00822	0.00354	59.62°
	MacAdam ellipse	0.3553)			
5000K	Single 5-step	(0.3447,	0.01370	0.00590	59.62°
	MacAdam ellipse	0.3553)			

	CIE-X	CIE-Y
5000K	0.3551	0.3760
	0.3376	0.3616
	0.3366	0.3369
	0.3515	0.3487

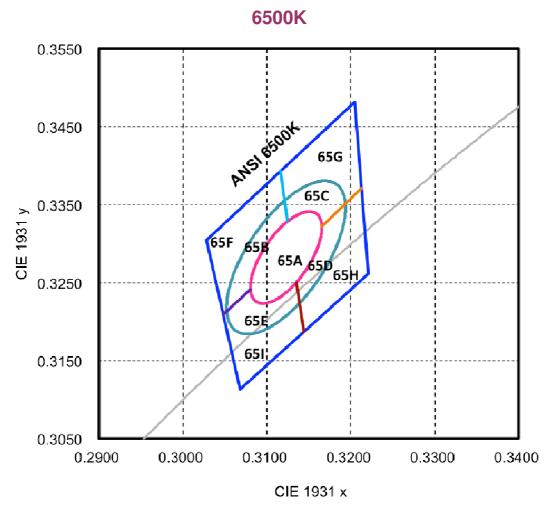




Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	a	b	Angle
5700K	Single 3-step	(0.3287,	0.00746	0.00320	59.09°
	MacAdam ellipse	0.3417)			
5700K	Single 5-step	(0.3287,	0.01243	0.00533	59.09°
	MacAdam ellipse	0.3417)			

	CIE-X	CIE-Y
5700K	0.3376	0.3616
	0.3207	0.3462
	0.3222	0.3243
	0.3366	0.3369





Nominal	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
ANSI CCT		Point (cx, cy)	а	b	Angle
6500K	Single 3-step	(0.3123,	0.00669	0.00285	58.57°
	MacAdam ellipse	0.3282)			
6500K	Single 5-step	(0.3123,	0.01115	0.00475	58.57°
	MacAdam ellipse	0.3282)			

	CIE-X	CIE-Y
6500K	0.3205	0.3481
	0.3028	0.3304
	0.3068	0.3113
	0.3221	0.3261

Note:

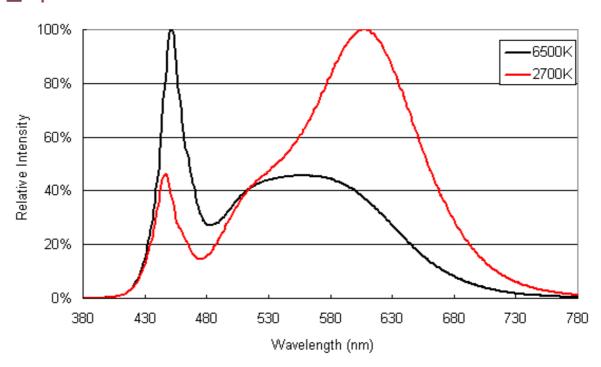
- (1) Correlated color temperature is derived from the CIE 1931chromaticity diagram
- (2) CIE measurement tolerance is ± 0.007
- (3) The luminous flux tolerance is ±7%
- (4) The forward voltage tolerance is ±1 V



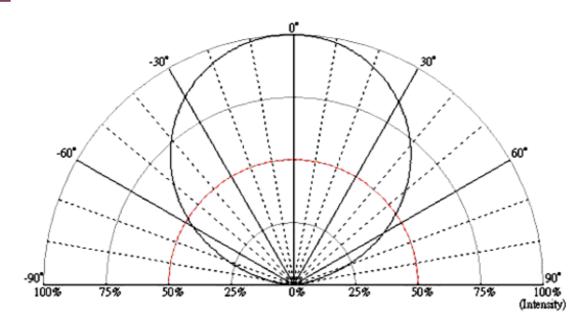
Characteristics

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Spectrum

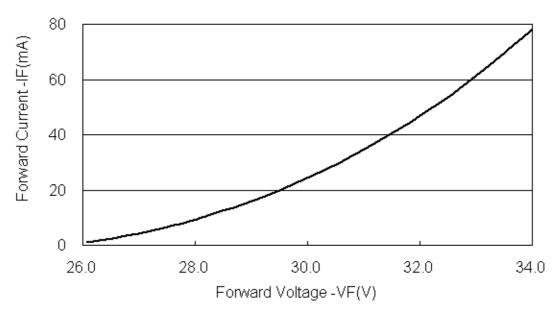


Radiation Pattern

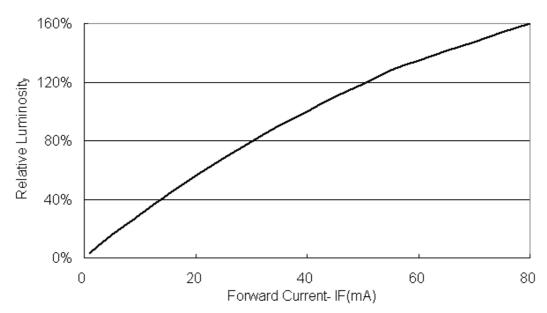




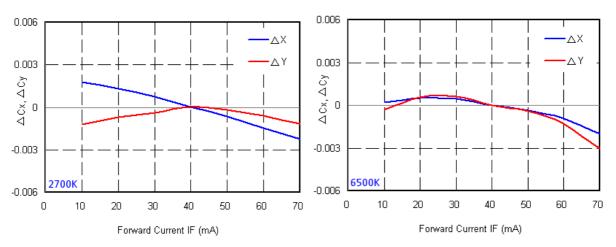
Forward Voltage vs. Forward Current



Forward Current vs. Relative Luminosity

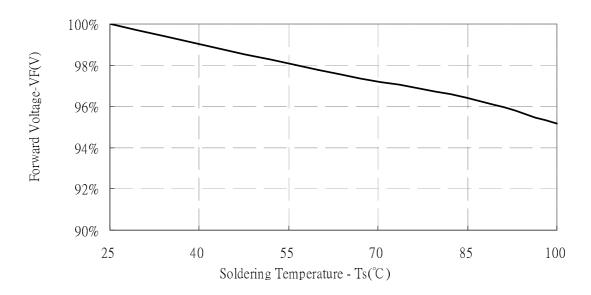


Forward Current vs. Chromaticity Coordinate

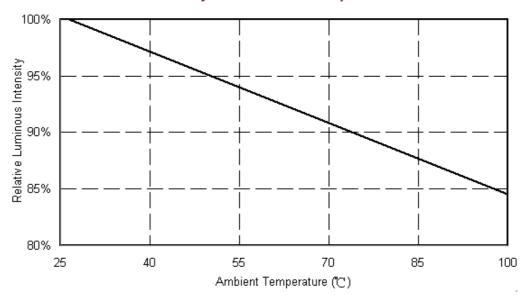




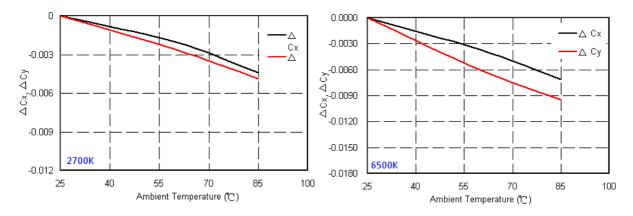
Relative Forward Voltage vs. Ambient Temperature



Relative Luminous Intensity vs. Ambient Temperature



Chromaticity vs. Ambient Temperature





Reliability

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Reliability test

Item	Condition	Current	Time/Cycle
Steady State Operating Life of	-40°C Operating	40mA	1000 Hrs
Low Temperature -40°C	-40 C Operating	40IIIA	1000 HIS
Steady State Operating Life of	60°C Operating	40mA	1000 Uro
High Temperature 60°C	oo C Operating	40MA	1000 Hrs
Steady State Operating Life of	85°C Operating	40m A	1000 Uro
High Temperature 85°C	65 C Operating	40mA	1000 Hrs
Steady State Operating Life of	105°C Operating	40mA	1000 Hrs
High Temperature 105°C	105 C Operating	40MA	1000 HIS
Low temperature storage -40°C	-40°C Storage	NA	1000 Hrs
High temperature storage 100°C	100°C Storage	NA	1000 Hrs
Steady State Operating Life of	60°C/000/ Operating	40 m A	1000
High Humidity Heat 60°€90%	60°C/90% Operating	40mA	1000 Hrs
Resistance to soldering heat on	pre-store@60°C, 60%RH for	NIA	0 Time
PCB (JEDEC MSL3)	52hrs Tsld max.=260°C 10sec	NA	3 Times
The word objects	-40°C/20minr ~5minr ~	NIA	000 Cycle -
Thermal shock	100°C /20min	NA	300 Cycles

Judgment Criteria

Item	Symbol	Test Condition	Judgment Criteria	
Forward Voltage Vf		40mA	ΔVf < 10 %	
Luminous Flux Iv		40mA	Δlv < 30 %	



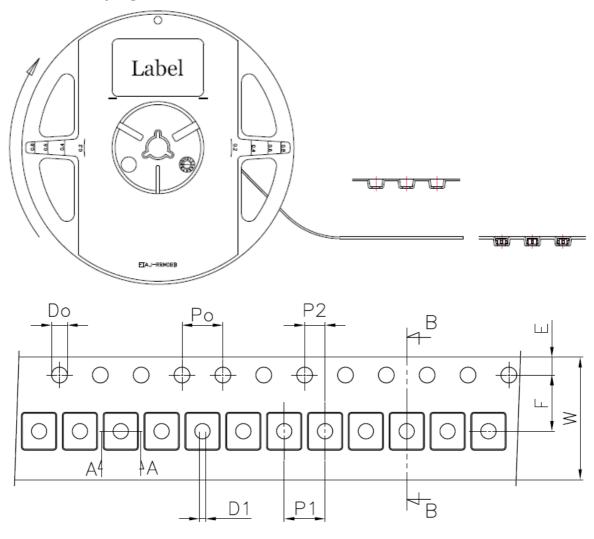
Packing

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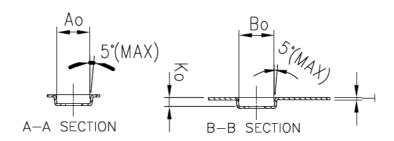
Label

Lextar Bin code: Vendor lot: M/N:

Carrier Taping







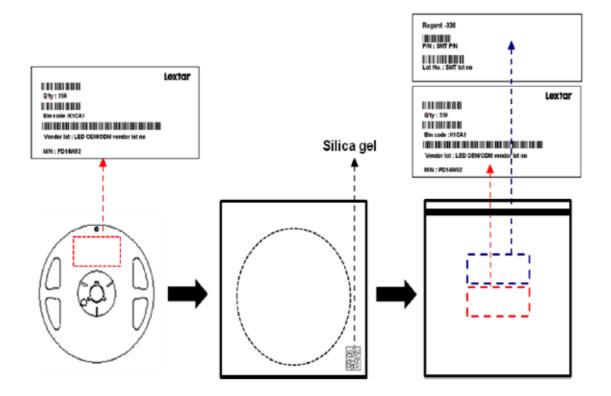
Unit:mm

symbol	Ao	Во	Ко	Po	P1	P2	Т
spec	3.25±0.10	3.50±0.10	0.78±0.10	4.00±0.10	4.00±0.10	2.00±0.05	0.20±0.05
symbol	E	F	Do	D1	W	10Po	
spec	1.75±0.10	5.50±0.05	1.50_0	1.50±0.10	12.0±0.30	40.00±0.20	

Notice:

- 1. 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.
- 2. Carrier camber shall be not more than 1mm per 100mm through a length of 250mm.
- 3. Ao & Bo measured on a place in the middle of the corner radii.
- 4. Ko measured from a place on the inside bottom of the pocket to top surface of carrier.
- 5. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole. 6. Surface resisivity $10^4 \sim 10^8$ ohm/sq.

Shield Bag Taping

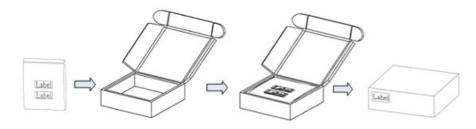




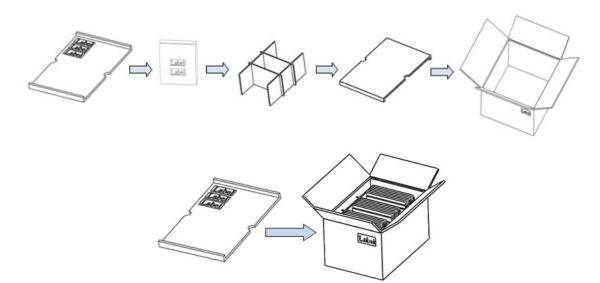
Packing Box

Туре	Large Box		Medium Box		Small Box	
Dimension	541X511X276r	mm	385X303X260mm		283X235x70mm	
Maximum Reels	7"X12mm Reel	64/R	7"X12mm Reel	21/R	7"X12mm Reel	4/R
Minimum Reels	7"X12mm Reel	32/R	7"X12mm Reel	9/R	7"X12mm Reel	1/R

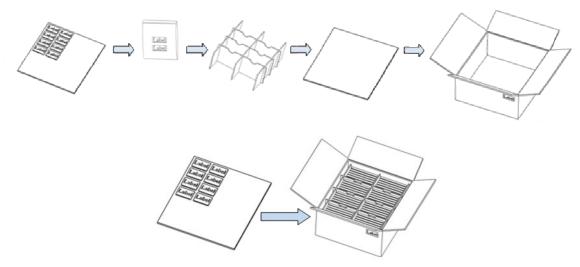
Small Box



Medium Box



Large Box





Precautions

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Safety Precautions

- The LED light output is too strong for human eyes without shield. Prevent eye contact directly more than seconds.
- Ensure operating under maximum rating.

Storage

- Before opening the package, the LEDs should storage under 30[°]C, 60[°]C, 81.
- After opening the package bag, the LEDs should be keep under 30℃, 60% RH.
 Recommend to use within 168 hrs. If unused LEDs remain, suggest to store into moisture proof bag or original package bag with moisture absorbent material such as silica gel. Reseal well is necessary.
- If the product exceeded the storage period or the moisture absorbent material faded away, baking treatment should be done by following conditions.
 Bake condition: 60℃, 12hours (One time only).

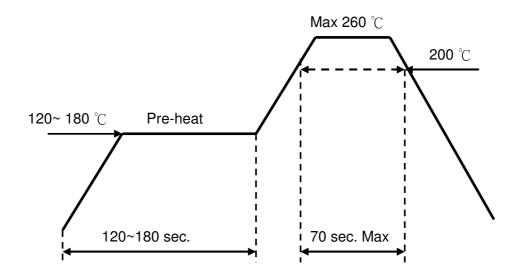
Soldering Notice and Conditions

- When soldering LEDs,
- Do not solder/reflow the same LED over two times.
- Recommend soldering conditions:

Reflow soldering: Pre-heat 150 $^{\circ}$ C max , 180 sec. max.

Peak 260 °C max, 10 sec. max.

Reflow temperature profile as below: (lead-free solder)





- When soldering, don't put stress on the LEDs
- After LEDs have been soldered, strongly recommend not to repair to keep the LEDs performance.

Static Electricity

- LED package is extremely sensitive to static electricity. It's recommended that
 anti-electrostatic glove and wrist band is necessary when handling the LEDs. All devices
 are also be grounded properly as well.
- Protection devices design should be considered in the LED driving circuit.

Cleaning

- If washing is required, recommend to use alcohol as a solvent.
- Recommend to avoid cleaning the LEDs by ultrasonic. If necessary, pre-test the LED is necessary to confirm whether any damage occur after the process.



Revision History

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Date	Contents	Writer	Approved
2015.09.01	New version	Kenis Hung	Berris Huang

Smart Lighting Amazing Life

Lextar Electronics Corp. is the leading LED (Light Emitting Diode)
maker integrating upper stream epitaxial, middle stream chip, and downstream package,
SMT and LED lighting applications. Founded in May, 2008, Lextar is a subsidiary of AU Optronics,
the leading TFT-LCD and solar PV manufacturer. Lextar's product applications include lighting and LCD backlight.
Lextar's manufacturing sites include Hsinchu and Chunan in Taiwan, and Suzhou in China.
The company turnover in 2010 is 266 million USD.